

Listing of Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Amendments to the Claims

1. (Previously Presented) A conductive lid adapted to function as a heat sink for an integrated circuit, said conductive lid comprising:
 - a recessed portion adapted to receive a die of said integrated circuit;
 - a foot portion extending from the top of said conductive lid to a surface adapted to be coupled to a substrate of said integrated circuit; and
 - a through-hole located in said foot portion, said through hole being tapered and adapted to receive an adhesive to secure said conductive lid to said substrate of said integrated circuit.
2. – 3. (Canceled)
4. (Previously Presented) The conductive lid of claim 1 wherein said through-hole comprises a multi-diameter through-hole.
5. (Previously Presented) The conductive lid of claim 1 wherein said through-hole comprises a first cylindrical portion and a second cylindrical portion.
6. (Original) The conductive lid of claim 1 wherein said through-hole is formed by injection molding.
7. (Original) The conductive lid of claim 1 wherein said through-hole is formed by drilling.

8. (Original) The conductive lid of claim 1 wherein said foot portion extends around said recessed portion.

9. (Original) The conductive lid of claim 8 further comprising a plurality of through-holes positioned in said foot portion.

10. (Original) The conductive lid of claim 9 wherein said plurality of holes are symmetrically spaced around said foot portion.

11. (Currently amended) An integrated circuit having a heat sink, said integrated circuit comprising:

a substrate;

a die positioned on said substrate; [[and]]

a conductive lid positioned over said die and coupled to said substrate, said conductive lid having a foot portion extending from a top of said conductive lid to said substrate and comprising at least one [[a]] multi-diameter through-hole; and an adhesive extending from said substrate into said through-hole.

12. – 13. (Canceled)

14. (Original) The integrated circuit of claim 11 wherein said through-hole comprises a conical through-hole.

15. (Original) The integrated circuit of claim 11 wherein said through-hole comprises a first cylindrical portion and a second cylindrical portion, said first cylindrical portion having a diameter which is different from said second cylindrical portion.

16. (Cancelled)

17. (Currently Amended) The integrated circuit of claim [[16]] 11 wherein said adhesive material comprises a thermally conductive epoxy.

18. (Cancelled)

19. (Original) The integrated circuit of claim 11 further comprising a thermal grease positioned between said die and said conductive lid.

20. (Original) The integrated circuit of claim 11 further comprising underfill positioned between said substrate and said conductive lid.

21-36. (Cancelled)

37. (Previously Presented) The integrated circuit of claim 11 wherein said through-hole comprises a frustum-shaped through-hole.